Preferred Device

# **Silicon Controlled Rectifiers**

# **Reverse Blocking Thyristors**

Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supply crowbar circuits.

- Glass Passivated Junctions with Center Gate Fire for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Constructed for Low Thermal Resistance, High Heat Dissipation and Durability
- Blocking Voltage to 800 Volts
- 80 A Surge Current Capability
- Insulated Package Simplifies Mounting
- 🔊 Indicates UL Registered File #E69369
- Device Marking: Logo, Device Type, e.g., MCR218-6, Date Code

| MAXIMUM RATINGS | $(T_J = 25^{\circ}C \text{ unless})$ | otherwise noted) |
|-----------------|--------------------------------------|------------------|
|-----------------|--------------------------------------|------------------|

| Rating  | Symbol                                | Value          | Unit             |
|---|---------------------------------------|----------------|------------------|
| Peak Repetitive Off–State Voltage <sup>(1)</sup><br>(T <sub>J</sub> = -40 to +125°C, Sine Wave 50 to<br>60 Hz, Gate Open) | V <sub>DRM,</sub><br>V <sub>RRM</sub> |                | Volts            |
| MCR218–6FP<br>MCR218–10FP   |                                       | 400<br>800     |                  |
| On-State RMS Current (T <sub>C</sub> = +70°C) <sup>(2)</sup><br>(180° Conduction Angles)                                  | IT(RMS)                               | 8.0            | Amps             |
| Peak Nonrepetitive Surge Current<br>(1/2 Cycle, Sine Wave 60 Hz,<br>T <sub>J</sub> = 125°C)                               | ITSM                                  | 100            | Amps             |
| Circuit Fusing (t = 8.3 ms)   | l <sup>2</sup> t                      | 26             | A <sup>2</sup> s |
| Forward Peak Gate Power<br>(T <sub>C</sub> = +70°C, Pulse Width $\leq 1.0 \mu$ s)   | PGM                                   | 5.0            | Watts            |
| Forward Average Gate Power<br>(T <sub>C</sub> = +70°C, t = 8.3 ms)  | PG(AV)                                | 0.5            | Watt             |
| Forward Peak Gate Current<br>(T <sub>C</sub> = +70°C, Pulse Width $\leq 1.0 \ \mu$ s)                                     | IGM                                   | 2.0            | Amps             |
| RMS Isolation Voltage ( $T_A = 25^{\circ}C$ ,<br>Relative Humidity $\leq 20\%$ )(9)                                       | V <sub>(ISO)</sub>                    | 1500           | Volts            |
| Operating Junction Temperature  | Тј                                    | -40 to<br>+125 | °C               |
| Storage Temperature Range   | T <sub>stg</sub>                      | -40 to<br>+150 | °C               |

(1) V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

(2) The case temperature reference point for all T\_C measurements is a point on the center lead of the package as close as possible to the plastic body.



## **ON Semiconductor**

http://onsemi.com

## ISOLATED SCRs (9\) 8 AMPERES RMS 400 thru 800 VOLTS





ISOLATED TO-220 Full Pack CASE 221C STYLE 2

| PIN ASSIGNMENT |       |  |  |  |
|----------------|-------|--|--|--|
| 1 Cathode      |       |  |  |  |
| 2              | Anode |  |  |  |
| 3              | Gate  |  |  |  |

#### ORDERING INFORMATION

| Device      | Package          | Shipping |
|-------------|------------------|----------|
| MCR218-6FP  | ISOLATED TO220FP | 500/Box  |
| MCR218-10FP | ISOLATED TO220FP | 500/Box  |

Preferred devices are recommended choices for future use and best overall value.

#### THERMAL CHARACTERISTICS

| Characteristic  |                 |                   |     | Max       |         | Unit     |  |
|---|-----------------|-------------------|-----|-----------|---------|----------|--|
| Thermal Resistance, Junction to Case  |                 | R <sub>θJC</sub>  |     | 2         | c       | °C/W     |  |
| Thermal Resistance, Case to Sink  |                 | R <sub>0CS</sub>  |     | 2.2 (typ) | c       | °C/W     |  |
| Thermal Resistance, Junction to Ambient   |                 | R <sub>θJA</sub>  |     | 60        | c       | °C/W     |  |
| Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds   |                 | т                 |     | 260       |         | °C       |  |
| ELECTRICAL CHARACTERISTICS (T <sub>C</sub> = 25°C unless otherwise note   | d.)             |                   |     |           | -       |          |  |
| Characteristic  | Sym             | bol               | Min | Тур       | Мах     | Unit     |  |
| OFF CHARACTERISTICS   | •               | · · ·             |     |           |         | •        |  |
| $ \begin{array}{l} \mbox{Peak Repetitive Forward or Reverse Blocking Current} \\ (V_D = Rated V_{DRM}, Gate Open) & T_J = 25^{\circ}C \\ T_J = 125^{\circ}C \end{array} $ | IDRM,<br>IRRM — |                   | _   |           | 10<br>2 | μA<br>mA |  |
| ON CHARACTERISTICS  |                 |                   |     |           |         |          |  |
| Peak Forward On–State Voltage(1)<br>(I <sub>TM</sub> = 16 A Peak)   |                 |                   | _   | 1         | 1.8     | Volts    |  |
| Gate Trigger Current (Continuous dc)<br>(V <sub>AK</sub> = 12 Vdc, R <sub>L</sub> = 100 Ohms)   | IG              | I <sub>GT</sub> — |     | 10        | 25      | mA       |  |
| Gate Trigger Voltage (Continuous dc)<br>(V <sub>AK</sub> = 12 Vdc, R <sub>L</sub> = 100 Ohms)   |                 |                   | _   | -         | 1.5     | Volts    |  |
| Gate Non-Trigger Voltage<br>(V <sub>AK</sub> = 12 Vdc, R <sub>L</sub> = 100 Ohms, T <sub>J</sub> = 125°C)   |                 | V <sub>GD</sub> 0 |     | -         | —       | Volts    |  |
| Holding Current<br>(V <sub>AK</sub> = 12 Vdc, Initiating Current = 200 mA, Gate Open)   |                 | IH —              |     | 16        | 30      | mA       |  |
| Turn-On Time $t_{g}$ (I <sub>TM</sub> = 8 A, I <sub>GT</sub> = 40 mAdc)   |                 | jt                |     | 1.5       | —       | μs       |  |
| Turn-Off Time ( $V_D$ = Rated $V_{DRM}$ ,<br>$I_{TM}$ = 8 A, $I_R$ = 8 A)<br>$T_J$ = 25°C<br>$T_J$ = 125°C  | t               | 7                 | _   | 15<br>35  | _       | μs       |  |

dv/dt

100

\_\_\_\_

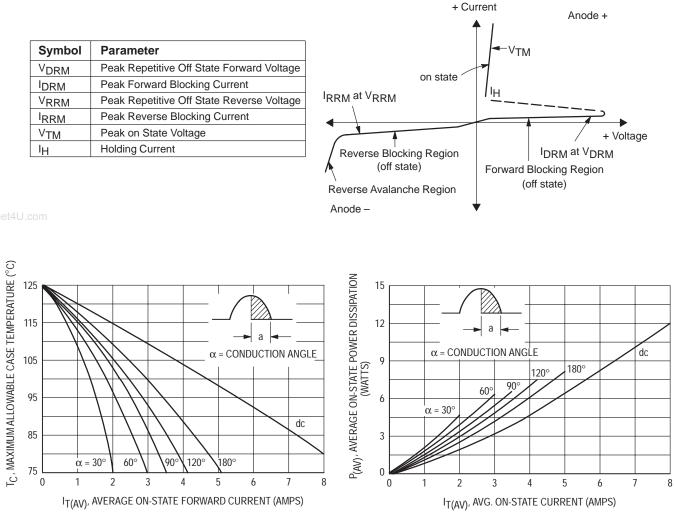
\_\_\_\_

Critical Rate-of-Rise of Off-State Voltage (Gate Open, V<sub>D</sub> = Rated V<sub>DRM</sub>, Exponential Waveform)

(1) Pulse Test: Pulse Width = 1 ms, Duty Cycle  $\leq 2\%$ .

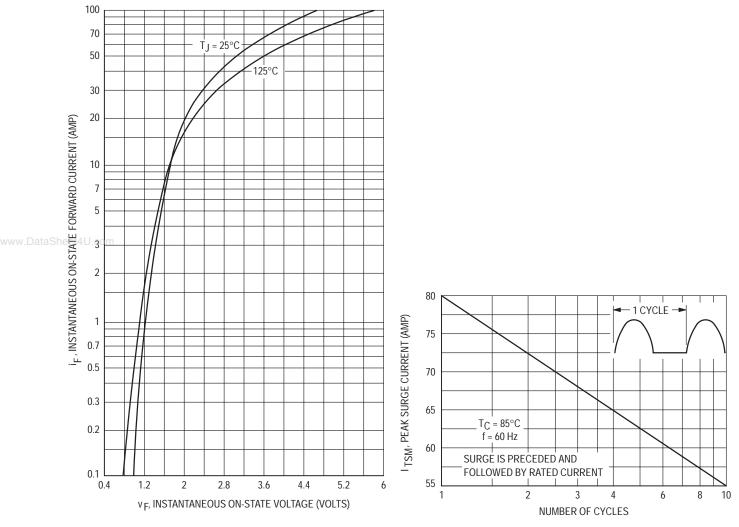
V/µs

#### Voltage Current Characteristic of SCR



**Figure 1. Current Derating** 

Figure 2. On-State Power Dissipation



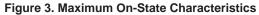


Figure 4. Maximum Non-Repetitive Surge Current

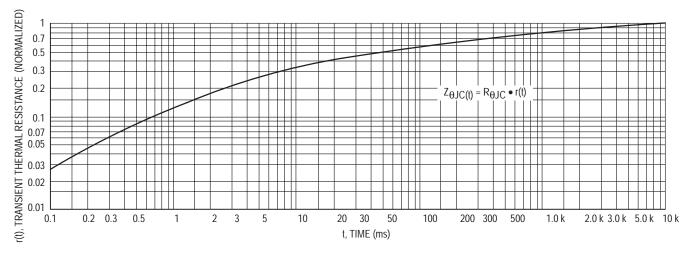


Figure 5. Thermal Response

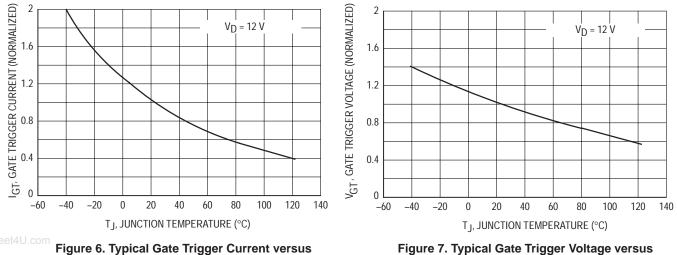




Figure 7. Typical Gate Trigger Voltage versus Temperature

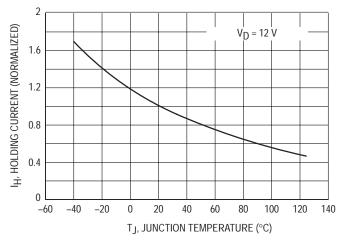
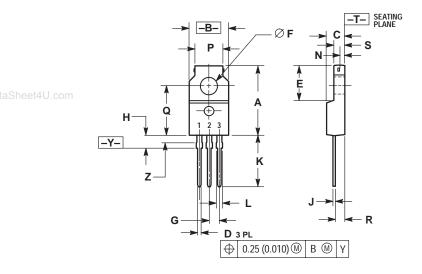


Figure 8. Typical Holding Current versus Temperature

#### PACKAGE DIMENSIONS

**ISOLATED TO-220 Full Pack** CASE 221C-02 **ISSUE C** 



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. LEAD DIMENSIONS UNCONTROLLED WITHIN DIMENSION Z.

|     | INCHES |           | MILLIN | IETERS |  |
|-----|--------|-----------|--------|--------|--|
| DIM | MIN    | MAX       | MIN    | MAX    |  |
| Α   | 0.680  | 0.700     | 17.28  | 17.78  |  |
| В   | 0.388  | 0.408     | 9.86   | 10.36  |  |
| С   | 0.175  | 0.195     | 4.45   | 4.95   |  |
| D   | 0.025  | 0.040     | 0.64   | 1.01   |  |
| Ε   | 0.340  | 0.355     | 8.64   | 9.01   |  |
| F   | 0.140  | 0.150     | 3.56   | 3.81   |  |
| G   | 0.100  | 0.100 BSC |        | BSC    |  |
| Н   | 0.110  | 0.155     | 2.80   | 3.93   |  |
| J   | 0.018  | 0.028     | 0.46   | 0.71   |  |
| К   | 0.500  | 0.550     | 12.70  | 13.97  |  |
| L   | 0.045  | 0.070     | 1.15   | 1.77   |  |
| Ν   | 0.049  |           | 1.25   |        |  |
| Р   | 0.270  | 0.290     | 6.86   | 7.36   |  |
| Q   | 0.480  | 0.500     | 12.20  | 12.70  |  |
| R   | 0.090  | 0.120     | 2.29   | 3.04   |  |
| S   | 0.105  | 0.115     | 2.67   | 2.92   |  |
| Ζ   | 0.070  | 0.090     | 1.78   | 2.28   |  |

STYLE 2: PIN 1. CATHODE 2. ANODE 3. GATE

# **Notes**

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